

Preliminary Amendment

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Title: SEMICONDUCTOR PACKAGE WITH PERFORATED SUBSTRATE

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

Abstract

A semiconductor package ~~(1; 18; 20)~~ comprises includes a substrate ~~(3; 21)~~ and a semiconductor chip ~~(2)~~ which includes an active surface with a plurality of chip contact areas ~~(13)~~. The chip ~~(2)~~ is electrically connected to the substrate ~~(3; 21)~~. The substrate comprises includes a sheet of core material ~~(5)~~, a plurality of upper conducting traces ~~(6)~~ and upper contact pads ~~(7)~~ on its upper surface, a second plurality of lower conductive traces ~~(8)~~ and external contact areas ~~(9)~~ on its bottom surface. A plurality of conducting vias ~~(10)~~ connect the conducting traces ~~(6)~~ and lower conducting traces ~~(8)~~. The substrate ~~(3; 21)~~ also includes a plurality of vent holes ~~(4; 22)~~ and a layer of solder resist ~~(15)~~ covering the upper and lower surfaces of the substrate ~~(3)~~ leaving the contact areas ~~(6 and 8)~~ free from solder resist ~~(15)~~.

~~{Fig. 1}~~